

PCN Number:	20191209000.1A		PCN Date:	Jan. 15, 2020	
Title:	Qualification of RFAB and TI Malaysia as additional Fab site and Assembly site options for select devices				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	Mar 9, 2020		Estimated Sample Availability:	Date provided at sample request.	
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input checked="" type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
PCN Details					
Description of Change:					
Revision A is to correct the Assembly Site Origin (22L) reference in the Changes to product identification resulting from the PCN section.					
This change notification is to announce the addition of RFAB and TI Malaysia as additional Fab site and Assembly site options for selected devices listed in the "Product Affected" section.					
Fab Site:					
Current Fab Site			Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
MIHO8	LBC7	200 mm	RFAB	LBC7	300 mm
Assembly Site:					
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly Site City		
TI Mexico	MEX	MEX	Aguascalientes		
TI Malaysia	MLA	MYS	Kuala Lumpur		
There are no Material differences between sites. Qual details are provided in the Qual Data Section.					
Reason for Change:					
Continuity of Supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Changes to product identification resulting from this PCN:					
Fab Site:					
Current Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
MIHO8	MH8	JPN	Ibaraki		
New Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
RFAB	RFB	USA	Richardson		
Assembly Site					
Current Assembly Site	Assembly Site Origin (22L)		ASO: MEX		
TI Mexico	Assembly Site Origin (22L)		ASO: MEX		
TI Malaysia	Assembly Site Origin (22L)		ASO: QAB MLA		

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:



MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT:
ITEM: 39
LBL: 5A (L) TO: 1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483S12
(P)
(2P) REV: (V) 0033317
(20L) CS0: SHE (21L) CCO: USA
(22L) AS0: MLA (23L) ACO: MYS

Product Affected:

Group 1: Adding RFAB and TI Malaysia Assembly site

SN65HVD182DDR	SN65LBC182DDR	THVD1500DR
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Group 2: Adding RFAB only

THVD1500D

Qualification Report

Approve Date 23-Sep-2019

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: THVD1500D	QBS Process Reference: TP S51217DSC	QBS Package Reference: SN65HVD1781AQDRQ1
AC	Autoclave 121C	96 Hours	-	3/231/0	3/231/0
CDM	ESD - CDM	1500 V	1/3/0	-	-
ED	Electrical Characterization	Per Datasheet Parameters	Pass	-	-
HAST	Biased HAST 130C/85%RH	96 Hours	-	3/231/0	3/231/0
HBM	ESD - HBM	4000 V	1/3/0	-	-
HBM	ESD - HBM	16000 V (Pins 6 and 7 Only)	1/3/0	-	-
HTOL	Life Test, 125C	1000 Hours	-	-	2/154/0
HTOL	Life Test, 135C	635 Hours	-	3/231/0	-
HTOL	Life Test, 140C	480 Hours	-	-	1/77/0
HTSL	High Temp Storage Bake 175C	500 Hours	-	-	1/45/0
HTSL	High Temp Storage Bake, 170C	420 Hours	-	3/231/0	-
LU	Latch-up	(Per JESD78)	1/6/0	-	-
TC	Temperature Cycle -65/150C	500 Cycles	-	3/231/0	3/231/0
WBP	Bond Pull	Wires	1/76/0	-	3/228/0
WBS	Ball Bond Shear	Wires	1/76/0	-	3/228/0

- QBS: Qual By Similarity
 - Qual Device THVD1500D is qualified at LEVEL1-260C
 - Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
 - The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
 - The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
 - The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles
- Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>
Green/Pb-free Status:
 Qualified Pb-Free (SMT) and Green

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